

### TSSOP14 4.90x3.90x0.95, 0.65P

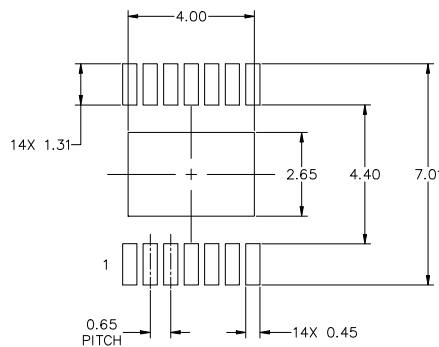
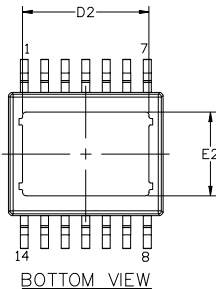
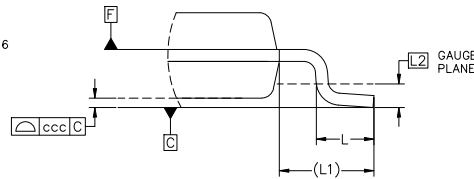
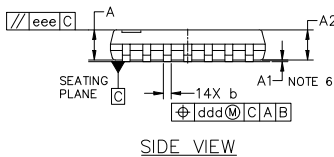
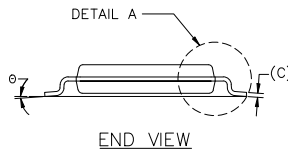
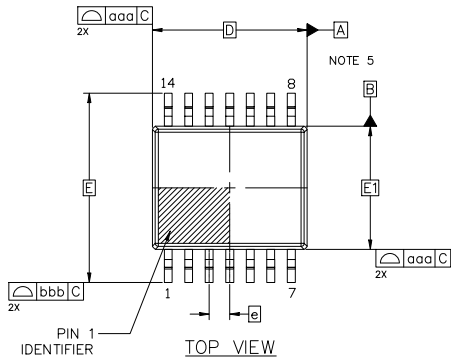
#### CASE 948BZ

#### ISSUE C

DATE 10 JUL 2025

**NOTES:**

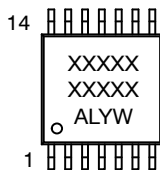
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M, 2018.
2. ALL DIMENSION ARE IN MILLIMETERS (ANGLE IN DEGREES).
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.127 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY INCLUDING THE THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS.
7. LEAD THICKNESS (c) AND LEAD WIDTH (b) INCLUDE PLATING THICKNESS.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.20	0.25	0.30
c	0.20 REF.		
D	4.90 BSC		
D2	3.90	4.00	4.10
E	6.00 BSC		
E1	3.90 BSC		
E2	2.55	2.65	2.75
e	0.65 BSC		
L	0.42	0.52	0.62
L1	1.05 REF.		
L2	0.25 BSC		
Ø	0*	4*	8*
TOLERANCE FOR FEATURE CONTROL FRAME			
aaa	0.10		
bbb	0.20		
ccc	0.08		
ddd	0.10		
eee	0.08		

### RECOMMENDED MOUNTING FOOTPRINT

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
 A = Assembly Location  
 L = Wafer Lot  
 Y = Year  
 W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>TSSOP14 4.90x3.90x0.95, 0.65P</b>	<b>PAGE 1 OF 1</b>

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